Tool ID: 224
Tool Location: 111

Equipment Information Sheet

Oxford Cobra ICP Dielectric

Manager: Jeremy Clark 607-254-6487
Backup: Philip Schneider 607-254-4931

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

SAFETY
USAGE RESTRICTIONS
SCHEDULING/SIGN-UP RESTRICTIONS
MATERIALS COMPATIBILITY CATEGORY

Minimum Tool Time: 15 minutes

Tool Category 1E: Silicon Based Materials and Select Dieletrics

Allowed	Not Allowed
Silicon Based Materials only	No Evaporated or Sputtered Films
Si, SiC, SiO_2 substrates	No Metal or Organic Films
All Furnace grown or deposited films	No Glass Substrates
PECVD Films	No III/V Compound Semiconductors
Select ALD dieletrics (SiO_2, SiN, HfO_2, HFN)	No High Vapor pressure materials
Spin on Glass and Spin on Dopants	Organic/Biology Molecules prepared-with or without Salt buffers

High Vapor Pressure Metals and Compounds are materials that have a vapor pressure above 1e-6 Torr at 400 C.

Additional Material Restrictions and Exceptions

- No metals allowed
- 100mm wafers only
- 5mm of resist must be removed from the edge of the wafer.
- Pieces may be temporarily bonded to a carrier wafer with Cool Grease

Last Updated: 06/23/2026